

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SBR8U60P5

8A SBR[®] SUPER BARRIER RECTIFIER POWERDI[®]

Features

- Ultra Low Forward Voltage Drop
- Patented Super Barrier Rectifier Technology
- · Soft, Fast Switching Capability
- 150°C Operating Junction Temperature
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: POWERDI5
- Case Material: Molded Plastic, "Green" Molding compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208
- Polarity: See Below
- Weight: 0.093 grams (approximate)

POWERDI5



Top View Bottom View

LEFT PIN O BOTTOMSIDE HEAT SINK

Note: Pins Left & Right must be electrically connected at the printed circuit board.

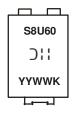
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|------------------------|----------|------------------|
| SBR8U60P5-13 | POWERDI5 | 5000/Tape & Reel |
| SBR8U60P5-13D (Note 5) | POWERDI5 | 5000/Tape & Reel |
| SBR8U60P5-7 | POWERDI5 | 1500/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.
- 5. "D" suffix designate for the 12mm Tape and Reel option.

Marking Information



S8U60 = Product Type Marking Code

J!! = Manufacturers' Code Marking

YYWW = Date Code Marking

YY = Last Two Digits of Year (ex: 13 for 2013)

WW = Week Code (01 - 53)

K = Factory Designator



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

| Characteristic | Symbol | Value | Unit |
|---|---|-------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _{RM} | 60 | ٧ |
| Average Rectified Output Current | lo | 8 | Α |
| Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load | I _{FSM} | 280 | А |
| Repetitive Peak Avalanche Power (1µs, +25°C) | P _{ARM} | 5,000 | W |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|--|--------------------------------------|-------------|------|
| Maximum Thermal Resistance Thermal Resistance Junction to Soldering (Note 6) Thermal Resistance Junction to Ambient (Note 7) | R _{eJS} R _{eJA} | 3 60 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -65 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

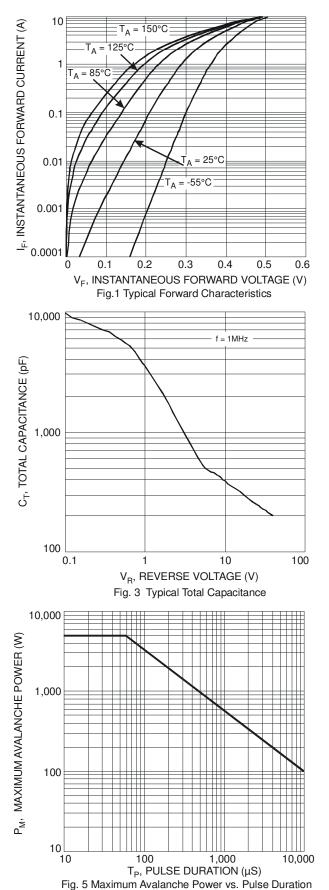
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|--------------------------|----------------|-----|------|------|------|--|
| Forward Voltage Drop | V _F | _ | 0.30 | 0.35 | V | $I_F = 1.0A, T_J = +25$ °C |
| | | _ | 0.46 | 0.53 | | $I_F = 8A, T_J = +25^{\circ}C$ |
| | | _ | _ | 0.5 | | $I_F = 8A, T_J = +125^{\circ}C$ |
| Leakage Current (Note 8) | I _R | _ | 0.12 | 0.6 | mA | V _R = 60V, T _J = +25°C |
| | | _ | _ | 100 | | $V_R = 60V, T_J = +125$ °C |

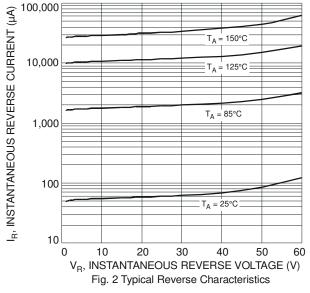
Notes:

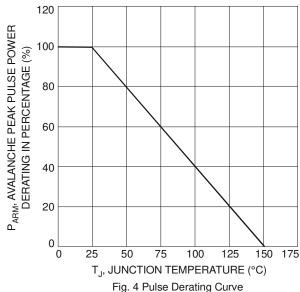
- 6. Theoretical R_{BJS} calculated from the top center of the die straight down to the PCB cathode tab solder junction.
 7. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com.
 8. Short duration pulse test used to minimize self-heating effect.

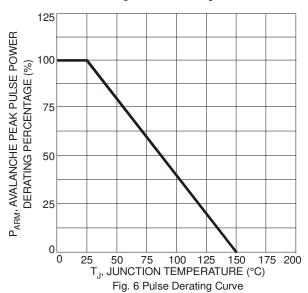




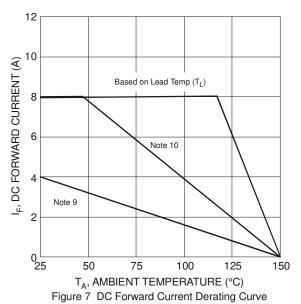


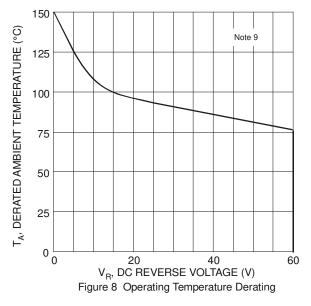










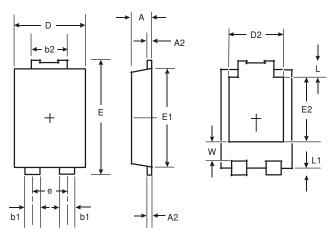


Notes: 9. Device mounted on FR-4 substate, 2oz copper, with minimum recommended pad layout.

10. Device mounted on FR-4 substate, 2oz copper, with 10cm x 10cm pad layout.

Package Outline Dimensions

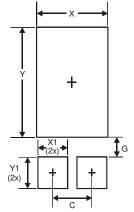
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



| POWERDI5 | | | |
|----------------------|-----------|------|--|
| Dim | Min | Max | |
| Α | 1.05 | 1.15 | |
| A2 | 0.33 | 0.43 | |
| b1 | 0.80 | 0.99 | |
| b2 | 1.70 | 1.88 | |
| D | 3.90 | 4.05 | |
| D2 | 3.054 Typ | | |
| Е | 6.40 | 6.60 | |
| е | 1.84 Typ | | |
| E1 | 5.30 | 5.45 | |
| E2 | 3.549 Typ | | |
| L | 0.75 | 0.95 | |
| L1 | 0.50 | 0.65 | |
| W | 1.10 | 1.41 | |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| С | 1.840 |
| G | 0.852 |
| X | 3.360 |
| X1 | 1.390 |
| Υ | 4.860 |
| Y1 | 1.400 |



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